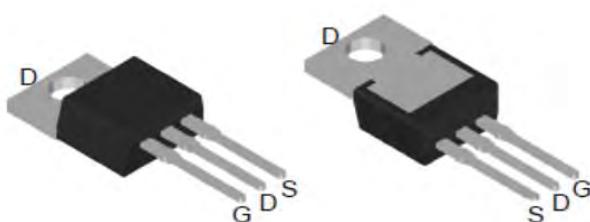


Trench N-channel Power MOSFET

MSR2R5N04CT
TO-220AB



V_{DS}	40	V
$R_{DS(on),TYP}@ V_{GS}=10\text{ V}$	2.0	mΩ
I_D	120	A

Features

- 1、Low on – resistance
- 2、Package TO-220AB
- 3、TrenchFET Power MOSFET

Applications

- 1、Load Switch for Portable Devices
- 2、DC/DC Converter

Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter		Rating	Unit
$V(BR)DSS$	Drain-Source breakdown voltage		40	V
V_{GS}	Gate-Source voltage		± 20	V
I_S	Diode continuous forward current	$T_C=25^\circ\text{C}$	--	A
I_D	Continuous drain current @ $V_{GS}=10\text{V}$	$T_C = 25^\circ\text{C}$	120	A
		$T_C = 100^\circ\text{C}$	90	A
I_{DM}	Pulse drain current tested ①	$T_C=25^\circ\text{C}$	400	A
EAS	Avalanche energy, single pulsed ②		1406	mJ
P_D	Maximum power dissipation	$T_C=25^\circ\text{C}$	150	W
$T_{STG,TJ}$	Storage and Junction Temperature Range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case	1.0	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	62	°C/W

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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Static Electrical Characteristics @ T_j=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	40	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V	--	--	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2.0	2.7	4.0	V
R _{D(on)}	Drain-Source On-State Resistance ④	V _{GS} =10V, I _D =30A	--	2.0	2.5	mΩ

Dynamic Electrical Characteristics @ T_j = 25°C (unless otherwise stated)

C _{iss}	Input Capacitance	V _{DS} =20V, V _{GS} =0V, f=1MHz	--	5677	--	pF
C _{oss}	Output Capacitance		--	872	--	pF
C _{rss}	Reverse Transfer Capacitance		--	529	--	pF
R _g	Gate Resistance	V _{GS} =0V, f=1MHz V _{DS} =0.015V,	--	3.3	--	Ω
Q _g (10V)	Total Gate Charge	V _{DS} =20V, I _D =30A , V _{GS} =10V	--	60	--	nC
Q _{gs}	Gate-Source Charge		--	14	--	nC
Q _{gd}	Gate-Drain Charge		--	10	--	nC

Switching Characteristics

Td(on)	Turn-on Delay Time	V _{DD} =20V, I _{DS} =30A, R _G =1.6Ω, T _j =25°C	--	14	--	ns
Tr	Turn-on Rise Time		--	49	--	ns
Td(off)	Turn-Off Delay Time		--	40	--	ns
Tf	Turn-Off Fall Time		--	7	--	ns

Source- Drain Diode Characteristics@ T_j = 25°C (unless otherwise stated)

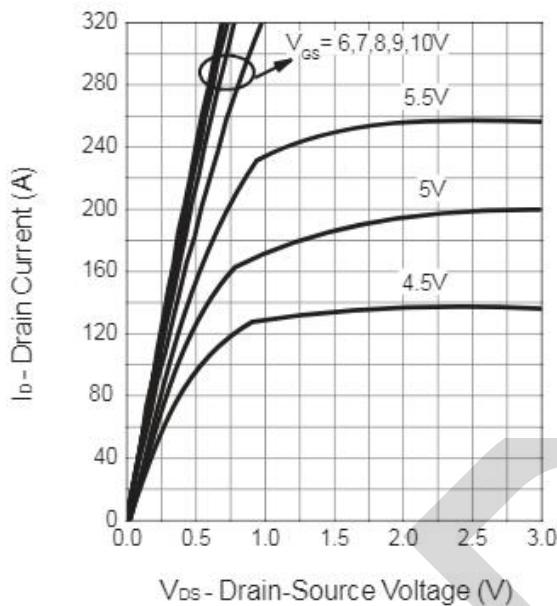
V _{SD}	Forward on voltage	I _{SD} =20A, V _{GS} =0V	--	0.8	1.0	V
T _{rr}	Reverse Recovery Time	T _j =25°C, I _{SD} =40A , V _{GS} =0V di/dt=100A/μs	--	40	--	ns
Q _{rr}	Reverse Recovery Charge		--	63	--	nC

NOTE: ① Repetitive rating; pulse width limited by max junction temperature.

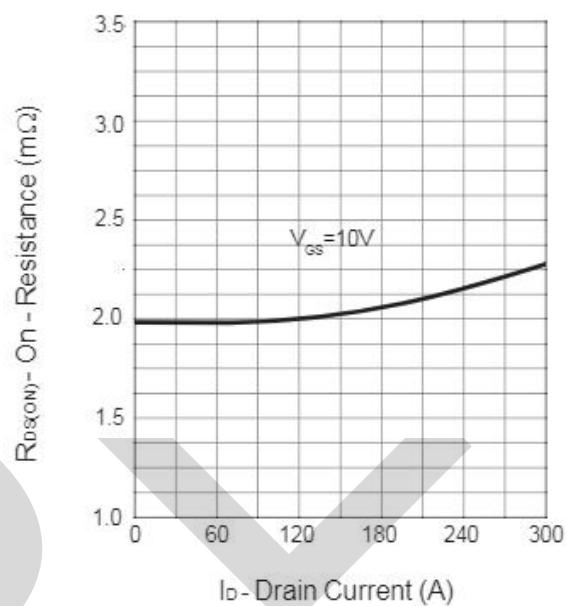
- ② Limited by T_{Jmax}, starting T_J = 25°C, L = 0.5mH, R_G = 25Ω, I_{AS} = 9A, V_{GS} = 10V. Part not recommended for use above this value
- ③ The power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C.
- ④ Pulse width ≤ 380μs; duty cycle≤ 2%.

Typical Characteristics

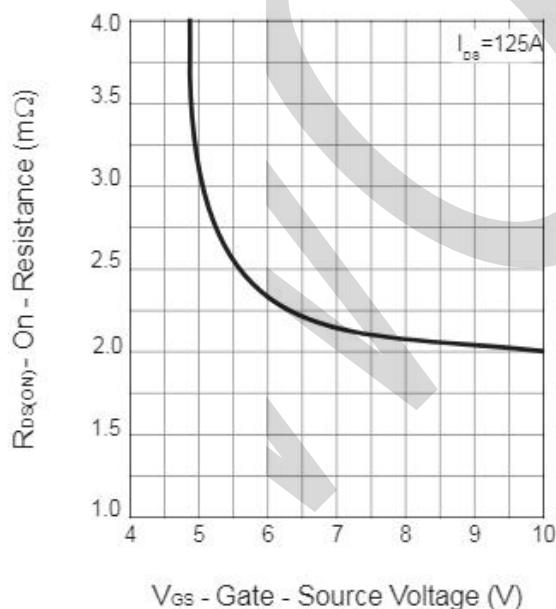
Output Characteristics



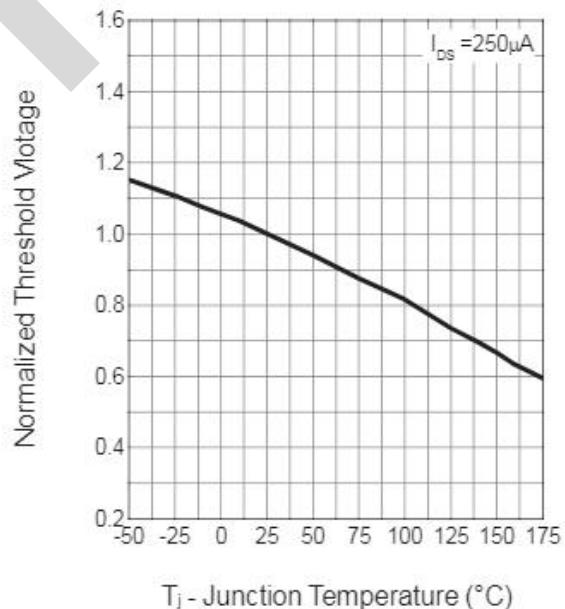
Drain-Source On Resistance



Drain-Source On Resistance

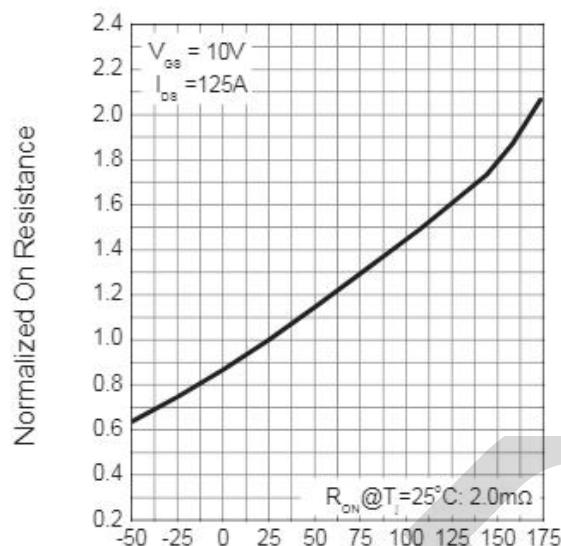


Gate Threshold Voltage

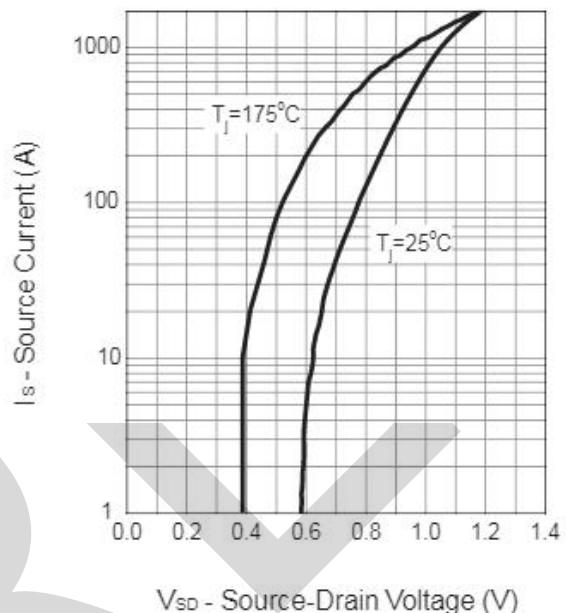


Typical Characteristics

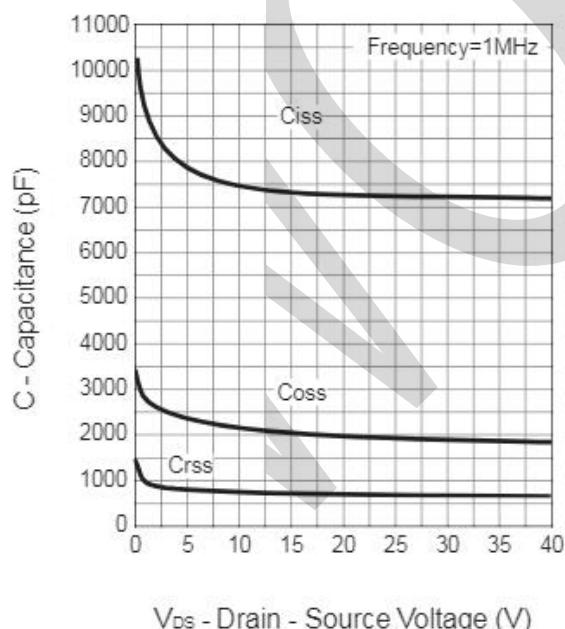
Drain-Source On Resistance



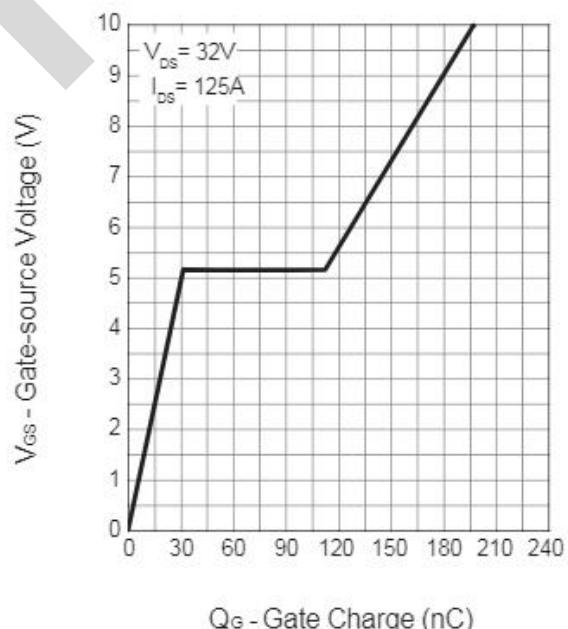
Source-Drain Diode Forward



Capacitance

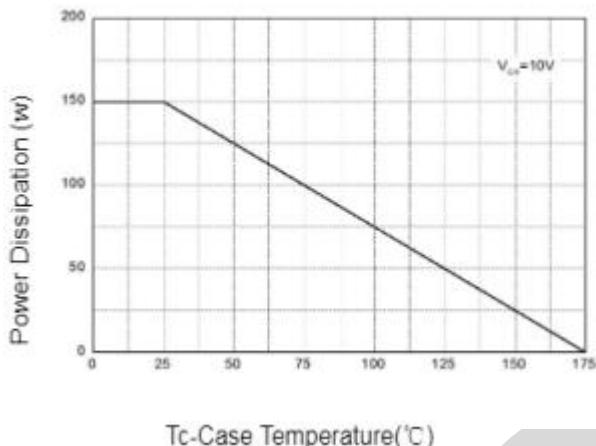


Gate Charge

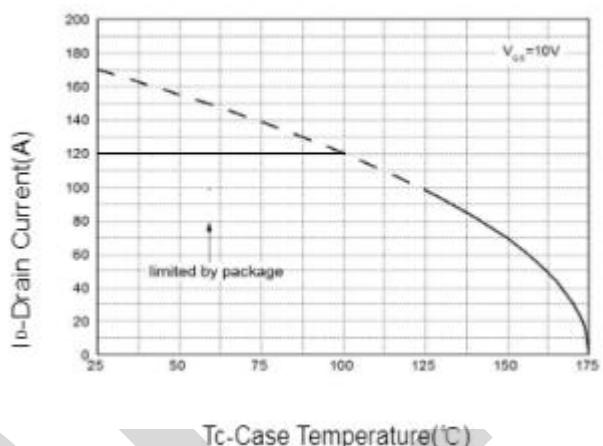


Typical Characteristics

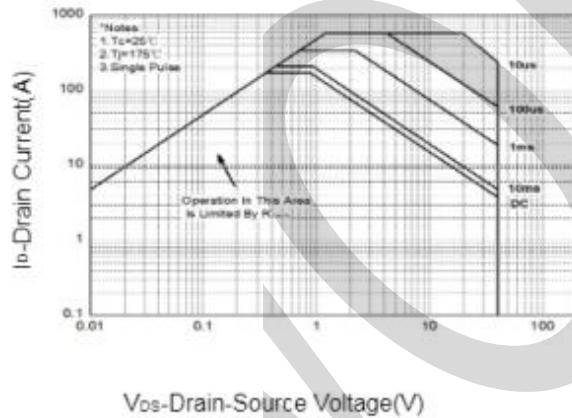
Power Dissipation



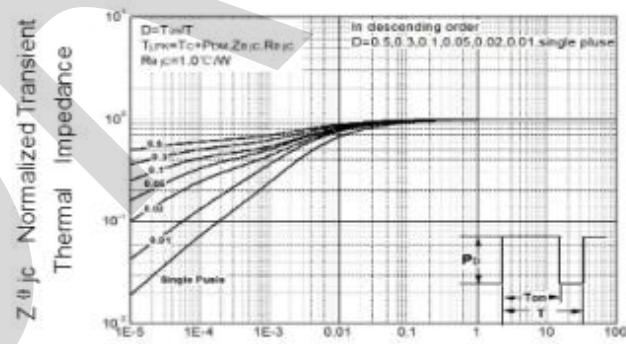
Drain Current



Safe Operation Area



Thermal Transient Impedance

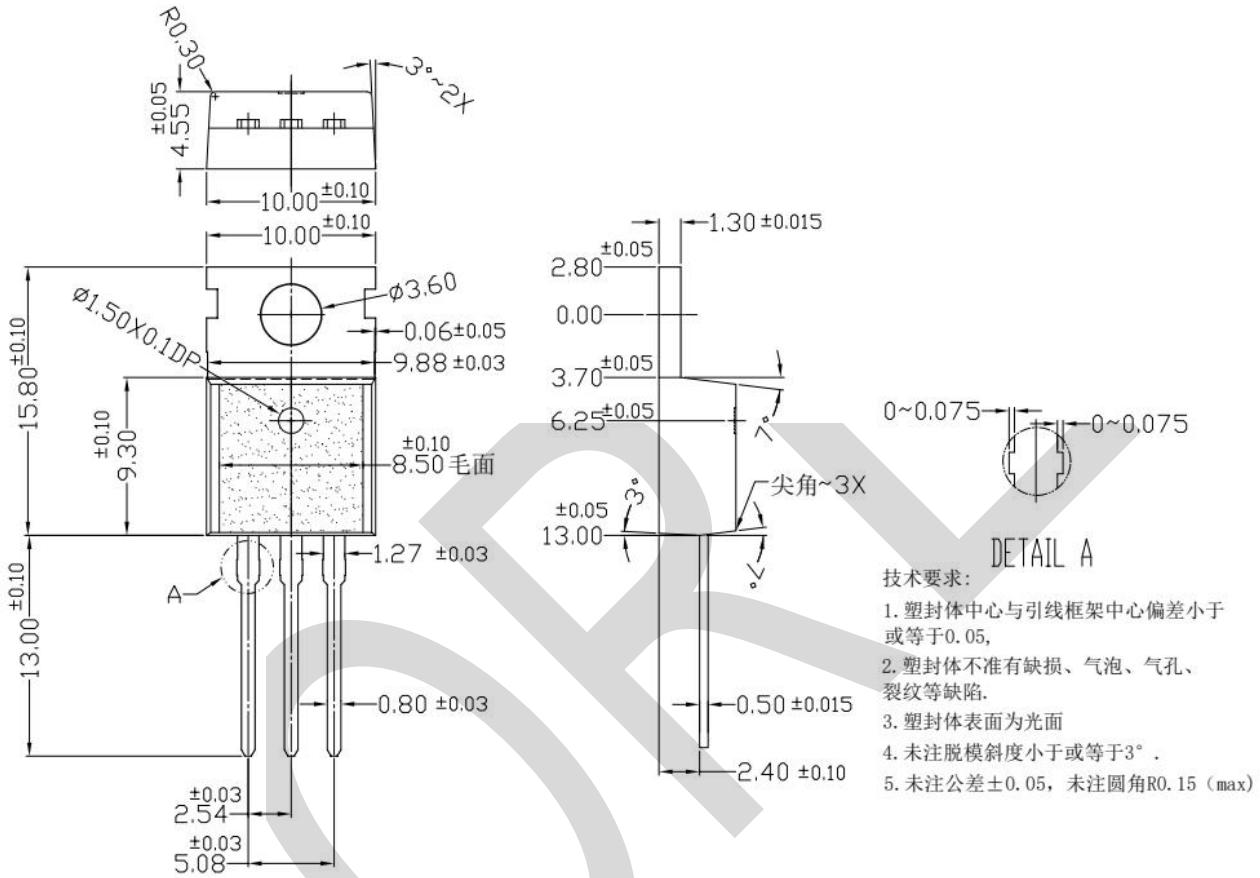


Maximum Effective Transient Thermal Impedance, Junction-to-Case

PACKAGE OUTLINE DIMENSIONS

Note:unit mm

TO-220AB



技术要求:

1. 塑封体中心与引线框架中心偏差小于或等于0.05,
2. 塑封体不准有缺损、气泡、气孔、裂纹等缺陷。
3. 塑封体表面为光面
4. 未注脱模斜度小于或等于3° .
5. 未注公差±0.05, 未注圆角R0.15 (max)